about us

ITW ECPS has 50 years of experience as a solution provider to electronic packaging systems. Over the years, through continuous effort in product innovation and customers collaboration in identifying and defining their needs, ITW ECPS has been able to continuously provide innovative technical services and products to our customers globally.

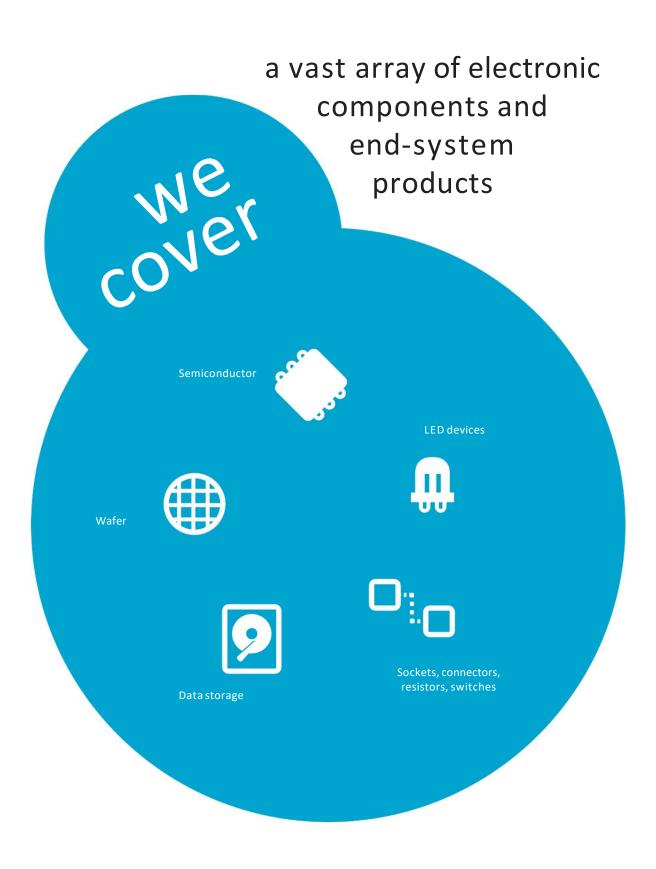
At ECPS, we are committed to invest in R&D, ensuring that we will continue to innovate and to roll out best in class service and unique product offerings in electronic packaging systems for our customers.

We are part of Illinois Tool Works, a global conglomerate listed in the New York Stock Exchange with USD 15 billion plus annual revenues.



physical and ESD protection for sensitive electronic components

barrier protection that resist all of nature's elements, including heat, fire, wind, UV, pests, and allergens



What separates us from the competition? Global Company, Local Presence



One-stop solution provider backed by unique enablers.

Design capability

- Design for manufacturability
- Build quality right from design

Material development

- Leverage on ITW global suppliers network
- Solid understanding of material science from commodity to engineering plastics
- "The right material for the right job"

Process development

- Expert manufacturing capabilities in extrusion, injection molding, precision thermoforming and multi-layer barrier sheet lamination
- Continuous improvement initiatives

Multiple manufacturing sites/strategic warehouses

- "The right quantity and quality at the right time"
- Proven experience in Just in time, Ship-to-Line,
 Supplier Managed Inventory, etc

Wafer packaging systems

Our wafer packaging systems product line is your cost effective solution to secure storage and transport of semiconductor wafers, ranges from 150 mm to 300 mm. Since 1999, our customers have enjoyed higher yields through a significant reduction in wafer breakage during storage, handling and transport between front end and back end sites.





Jedec trays

We offer Jedec trays that reflect our relentless pursuit in design philosophy to combine the best of both worlds - maximum durability and light weight.

Each of our tray designs is subjected to rigorous testing and qualification.



Chip Fit Analysis



Load flex and deflection test



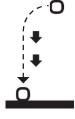
Multi-cycle bake test



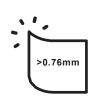
Strapping test



Impact test



Drop test



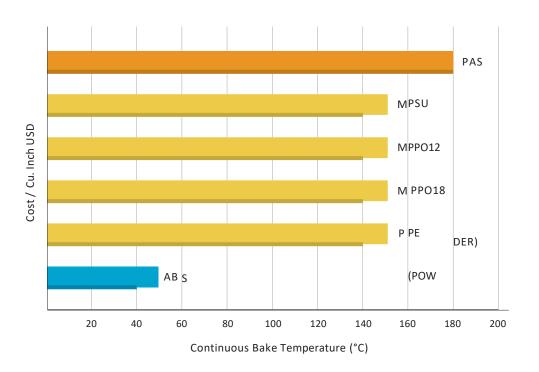
Warptest



ESD test

Proprietary and unique design techniques Deliver maximum tray structure strength with optimum use of materials Precise and accurate pocket pitching Incorporating many poka yoke design features Design for maximum reuse cycles Freight cost saving Critical for small and light devices error free placement A breakthrough design for 2.5 x 2.5 mm LGA flippable tray - the world's smallest to-date Prevent device misplacement and damage

We offer various materials for a wide range of operational temperature requirements. Our full range of materials offering will be able to satisfy your cost and performance considerations.







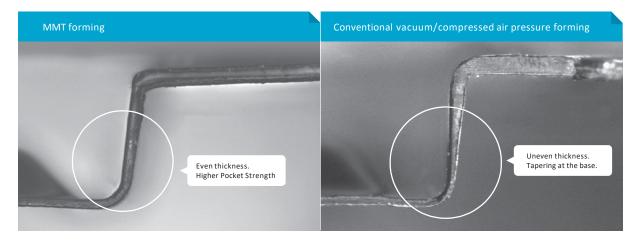
Features

- Strong pocket
- Uniform wall thickness
- Smaller wall draft angles
- Proven carrier cover tane system

Benefits

- Maximum device protection
- Prevent device tilting
- Designed for high speed operating environments
- High material strength
- Cover tape tear-free, broken-seal free

MMT forming vs conventional vacuum/compressed air pressure forming





is your answer to the industry challenge in bare die and wafer level applications. We offer Polycarbonate material and male rotary forming technology that deliver high performance for this "mission critical" application. Sharp pocket corners, low ionic contamination and stable dimensions are the must haves in your selection criteria.





Features

- Sharp pockets
- Low ionic contaminant and clean room compatibility
- Conductive Polycarbonate
- Unit clearance to pocket clearance complies to FIA763
- Corner relief feature

Benefits

- Secure chip placement
- Prevent device tilt
- Avoid vision false alarm triggers
- Reduced unnecessary machine stoppages
- Prevent chip contamination
- Maintain excellent solderability
- Stable dimensions and high material strength
- Designed for high speed operating environments
- Zero sharp device edges getting stuck or chipping in pocket



Cover tape

When it comes to reliability performance, carrier tape and cover tape system compatibility is extremely important. Our systems are simulated under hot and cold conditions to ensure they hold up under extreme weather conditions.

ST Cover Tape and 24mm Carrier Tape

Sealing Machine Peeling Machine Sealing Shoe

: Systemation

: GPD PBFT Model 856VS : 0.45mm x 80mm

Sealing Pressure : 35 Ps

Carrier Tape Part : 24mm Carrier Tape

ealing Temperature : 200° C

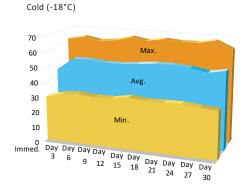
Peeling Speed : 300 mm/r

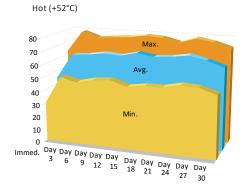
Cold (-18°C)

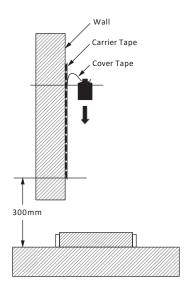
	Immed.	Day 3	Day 6	Day 9	Day 12	Day 15	Day 18	Day 21	Day 24	Day 27	Day 30
Min.	30	33	34	33	33	35	34	34	34	33	32
Max.	63	65	63	64	67	65	67	66	66	68	63
Avg.	45	53	53	52	52	53	54	54	53	51	53
Range	33	32	29	31	34	30	33	32	32	35	31

Hot (+52°C)

	Immed.	Day 3	Day 6	Day 9	Day 12	Day 15	Day 18	Day 21	Day 24	Day 27	Day 30
Min.	30	51	48	51	52	48	50	50	53	52	48
Max.	63	79	75	76	77	79	78	75	79	77	73
Avg.	45	64	65	67	66	69	67	68	70	67	63
Range	33	28	27	25	25	31	28	25	26	25	25







High speed cover tape tear test.

Today's PCB assembly industry going for higher throughput can push detaping speeds up to 10,000 mm/minute. At these speeds, a robust system is a must. We don't take chances. We simulate our tape and reel system to survive these conditions, which mean we go above typical industry peel force tests of 300 mm/minute.

ST series cover tape

Features

- Wide range of sealing temperatures
- Stable antistatic properties
- Consistent seal within EIA 481 specification

Benefits

- Wide sealing process window
- Machine adjustment friendly
- No static cling
- Superior ESD protection
- Cover tape tear-free, broken-seal free

Bond profile

Peel Force (gm) 100 80 60 40 20 145 155 165 175 185 195 205 215 Sealing Temperature (°C)

ST cover tape

Tape Tested :12mm CPS carrier tape

Sealing Pressure :35psi

Dwell time :250ms

Sealing shoe :80mm (L) x 0.45mm(W)



STi series cover tape

Features

- 40% stronger
- Reinforced top layer
- Excellent clarity and transparency
- Low variation at different temperature ranges
- Sealant side treated to 10° level surface resistivity

Benefits

- Designed for high speed operating environments
- Ease device visual inspection
- Minimal machine and process adjustment during part change over
- Superior ESD protection
- No static cling

Bond profile

Peel Force (gm) 100 80 60 40 20 145 155 165 175 185 195 205 215 Sealing Temperature (°C)

STi cover tape

Tape Tested :12mm CPS carrier tape

Sealing Pressure :35psi
Dwell time :250ms

Sealing shoe :80mm (L) x 0.45mm(W)

Shipping reels

We have a wide range of High Impact Polystyrene (HIPS) shipping reel open tools. They are available in antistatic treated, static dissipative or conductive materials. Two choices of designs are available to meet your needs.

Ultra sonic welded reels



Features

- Light weight

Benefits

- Freight cost saving



Snap fit reels

Features

- Ship in halves
- Assemble by snapping 2 halves together
- Rigid flange
- Only 4 hub widths needed to cater 7 carrier tape width configurations (8 to 56 mm)

Benefits

- Compact, Freight cost saving
- Secure locking
- Design for heavy duty and re-use
- Lower inventory holding

Shipping tubes

Standard PVC

For more than 50 years, the semiconductor industry has been relying on shipping tubes as the main medium to carry their components between Assembly and Test operations or to their end customers. Its popularity remains today for two simple reasons - economy and flexibility. We carry more than one thousand open tools that run from through-hole, surface mount to leadless packages (QFN, MLP, etc). Our products also serve the connector, LED and passive component customers.

Features	Benefits			
Good impact strength	Crack free tubes			
Stable dimension	 Excellent smooth interfacing with handlers 			
Critical dimension control within +/- 5 mils	Higher productivity, more man-to-machine ratio			
Short cycle time	Short lead time			



Polycarbonate

Polycarbonate shipping tubes are our high performance shipping tube series. Our deep knowledge in shipping tube design, polymer science and extrusion processing technology allows us to produce shipping tubes with +/- 2 mils (+/- 50 microns) of dimensional tolerance control. This unique tight tolerance capability helps many of our customers to improve their machine uptime, reduce scrap and minimize rework.

Features Tight tolerance. Critical dimension control +/- 2 mils Superb clarity/transparency Package guide profile design High impact strength Accurate unattended high speed device loading and unloading Ease of visual inspection Prevent device piggy back, shingling and unit rotation

"Green materials"

We are committed to global environment preservation by building a strong sustainability mindset across our organization. We walk the talk.

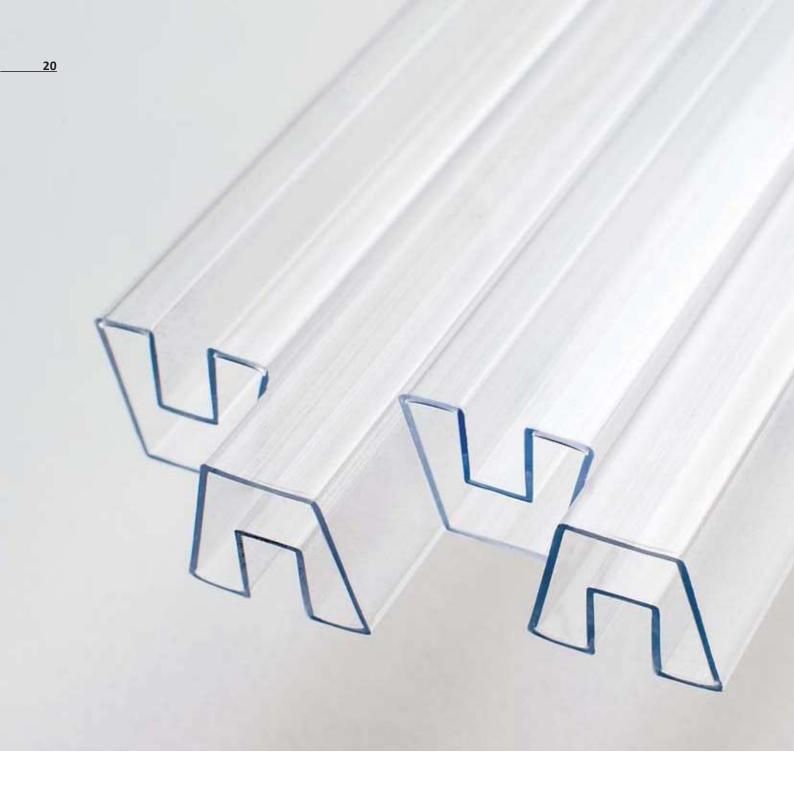
We actively support the 3R concept -- Reduce, Reuse and Recycle.

We are constantly looking for opportunities to introduce products that can help to minimize the impact to the environment. A wide choice of "green materials" such as PS¹,PC² and PETG³ polymer products are a testimony to delivering that commitment.

PS¹ shipping tubes

Features	Benefits
Halogen free	Reduced environmental impact
 Improved clarity/transparency and impact strength 	 Good clarity/transparency without compromising impact strength
Available in clear or translucent	





PETG³ shipping tubes

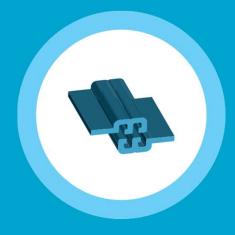
Features	Benefits
Halogen free	Reduced environmental impact
Strongest impact strength	Excellent for heavy duty big packages
 Excellent clarity/transparency 	 Application examples: microprocessor heat sink and ceramic TO packages.

- 1. Polystyrene (PS)
- 2. Polycarbonate (PC)
- 3. Polyethylene Terepthalate Glycol (PETG)



You can rely on MaxiGrip's barrier closure protection products in unpredictable environments. Our state-of-the-art barrier technology joining solutions are ideal for applications that must withstand extreme conditions. Our products keep what is inside an assembly protected from the environment and prevents undesired external elements that cause damage or contamination from entering.

We offer flat or horizontal plane closures (MaxiGrip) and top or vertical closures (U-MaxiGrip) that are re-sealable and practical.





MaxiGrip

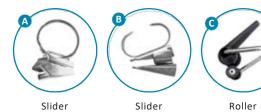
U-MaxiGrip

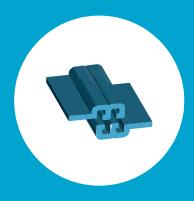
MX series zipper(MaxiGrip)

MaxiGrip products are available in a variety of strengths and sizes with different closure tools

Features	Benefits			
In-line/horizontal type closure	Standard closure/attachment/seal replacement			
Slider actuated opening and closure	Liquid and gas resistant barrier/seal			
Roller actuated closure for long runs	Modular connections and seals			
Cut to length with optional easy end termination	Weld, glue, or sew on			

Model	No. of Tracks	Slider & Rollers
MX20	2 Track	A B C
MX28	2 Track	A B C
MX39	2 Track	A B G
	3 Track	A B C
MX53	3 Track	A B C
MX59	2 Track	A B C







MaxiGrip

U-MaxiGrip

UMX series (U-MaxiGrip)

U-MaxiGrip is a heavy duty zip locking closure specified for top or vertical seal applications. UMaxiGrip plastic zippers are available in a variety of strengths and sizes with different closure tools.

Features	Benefits
 Vertical/top-of-bag type closure Manual opening and closure Air & liquid tight barrier/seal Quiet operation 	 Liquid & Gas tight barrier/seal Bags, long term storage, secondary containment applications Pressure and/or vacuum barriers Weld or glue on

Model	No. of Tracks	Slider & Rollers
UMX20	2 Track	Manual by hand
UMX28	2 Track	Manual by hand
UMX39	2 Track	Manual by hand
	2 Track 1Fold-back flanger	and Roller
	2 Track 2 Fold-back flangers	
	2 Track 2 Stand-Up flangers	
	3 Track	





Drypack DB 3000 series moisture barrier bag

Drypack DB 3000 series is specifically designed to provide superior moisture vapor barrier yet fully transparent. This proprietary film lamination structure enables you to see through to the contents and perform barcode scanning.

Features	Benefits
 Low MVTR @ <0.05g/100in²/day 	Enhanced contents protection from moisture
 Transparent 	 Easy content identification and bar code scanning
Minimal charge retention	Safeguards static sensitive devices



Drypack DB 38XX series moisture barrier bag

Drypack DB 38XX series is a high barrier foil laminated film developed for semiconductor industry. It is a popular choice to vacuum pack tape and reel, IC trays or shipping tubes.

Features	Benefits
Superior MTVR, < 0.0003 g/100 in²/day	Excellent vacuum retention
A solid Aluminum foil middle layer	Total EMI/ESD protection
More than 25 lbs puncture resistant	 Prevent bag puncture against sharp corners of IC tray or shipping tube



Nylon PE is ideal for packing sharp objects such as fastener where puncture resistance and durability are required. The film is transparent clear, strong and vacuum heat sealable.

Features Reinforced with nylon Transparent clear Readily heat sealable Benefits High puncture resistant Contents remain visible while protected Readily heat sealable

Selection Chart

			Nylon PE Bag	RCAS 4150/ES 2150 Static Shielding Bag	Drypack DB 3000 Series Moisture Barrier Bag	Drypack DB 38XX Series Moisture Barrier Bag
		Physica	l Properties			
	Test Method	Unit				
Thickness	ASTM D374	Mil	2.5-8.0	3.0	3.0	3.6-7.0
Light Transmission		%	100	40	55	None
Puncture Resistance	FTMS 101C Method 2065	lbs	>15	>12	>15	>25
Heat Seal Strength	ASTM F88-99	lbs/in	>13	>10	>11	>15
Moisture Vapor	ASTM-F-1249-90	g/100in²/day	N/A	N/A	<0.05	<0.0003
Transmission Rate (MVTR)	(37.8°C, 90%RH)					
		Electrica	al Properties			
	Test Method	Unit				
Surface Resistivity	EOS/ESDS11.11	ohm/sq	< 1x1012	< 1x1012	< 1x1012	< 1x10 ¹²
Electrostatic Decay	FTMS 101C Method 4046	sec	N/A	< 0.05	< 0.05	< 0.05
Energy Test	EOS/ESDS11.31	nanojoules	N/A	< 20	< 15	< 10
Capacity Probe	EIA-541	volts	N/A	< 25	< 25	< 25
		Cleanline	ss Propertie	5		
	Test Method	Unit				
LPC	@>0.5um	counts/cm ²	<3000	<3000	< 3000	<3000
Outgassing	GC-MS	ng/cm²	< 1709	< 1709	< 1709	< 1709
Ionic Contamination	Chloride	ng/cm ²	< 10	< 10	< 10	< 10
	Nitrate	ng/cm ²	< 100	< 100	< 100	< 100
	Sulphate	ng/cm ²	< 10	< 10	< 10	< 10

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